

Title (en)  
DISTRIBUTION CONNECTING MODULE

Title (de)  
VERTEILERANSCHLUSSMODUL

Title (fr)  
MODULE DE RACCORDEMENT DE DISTRIBUTION

Publication  
**EP 1658660 A1 20060524 (DE)**

Application  
**EP 04764006 A 20040812**

Priority  
• EP 2004009002 W 20040812  
• DE 10339844 A 20030829

Abstract (en)  
[origin: DE10339844B3] A casing (2) has a hollow space to hold a printed circuit board (PCB). Input/output contacts on opposite front sides of the casing link to the PCB so as to detach. Input contacts (IC) form a connection strip (CS) (5) with insulation displacement contacts. The CS carrying the IC link to the casing via a front part so as to detach.

IPC 1-7  
**H01R 12/18**; **H01R 9/24**

IPC 8 full level  
**H01R 9/24** (2006.01); **H01R 12/18** (2006.01); **H01R 12/55** (2011.01); **H01R 13/518** (2006.01); **H01R 13/74** (2006.01); **H02G 15/06** (2006.01); **H04Q 1/14** (2006.01); **H01R 4/64** (2006.01); **H04Q 1/06** (2006.01)

CPC (source: EP KR US)  
**H01R 9/24** (2013.01 - EP US); **H01R 12/71** (2013.01 - KR); **H01R 12/721** (2013.01 - EP US); **H01R 13/518** (2013.01 - EP US); **H01R 13/748** (2013.01 - EP US); **H01R 31/02** (2013.01 - KR); **H04Q 1/116** (2013.01 - EP US); **H04Q 1/142** (2013.01 - EP US); **H04Q 1/149** (2013.01 - EP US); **H01R 4/64** (2013.01 - EP US); **H01R 9/2416** (2013.01 - EP US); **H01R 9/2483** (2013.01 - EP US); **H04Q 1/06** (2013.01 - EP US); **H04Q 1/146** (2013.01 - EP US); **H04Q 2201/02** (2013.01 - EP US); **H04Q 2201/14** (2013.01 - EP US); **H04Q 2201/802** (2013.01 - EP US)

Citation (search report)  
See references of WO 2005029647A1

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)  
**DE 10339844 B3 20050127**; AR 045514 A1 20051102; AT E375610 T1 20071015; AU 2004305612 A1 20050331; AU 2004305612 B2 20090625; BR PI0413805 A 20061017; CA 2534960 A1 20050331; CA 2534960 C 20090602; CN 100446344 C 20081224; CN 1591984 A 20050309; CY 1107127 T1 20121024; DE 502004005223 D1 20071122; DK 1658660 T3 20071217; EP 1658660 A1 20060524; EP 1658660 B1 20071010; ES 2293320 T3 20080316; HR P20070520 T3 20071231; KR 100743407 B1 20070730; KR 20060060718 A 20060605; MX PA06002137 A 20060517; MY 136954 A 20081231; NZ 545051 A 20080630; PL 1658660 T3 20080229; PT 1658660 E 20071121; RU 2006110045 A 20060810; RU 2309496 C2 20071027; TW 200518407 A 20050601; TW I239125 B 20050901; UA 81968 C2 20080225; US 2006286824 A1 20061221; US 2008293268 A1 20081127; US 7407389 B2 20080805; US 7618261 B2 20091117; WO 2005029647 A1 20050331; ZA 200601687 B 20070425

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**DE 10339844 A 20030829**; AR P040103077 A 20040827; AT 04764006 T 20040812; AU 2004305612 A 20040812; BR PI0413805 A 20040812; CA 2534960 A 20040812; CN 03125572 A 20030918; CY 081100017 T 20080108; DE 502004005223 T 20040812; DK 04764006 T 20040812; EP 04764006 A 20040812; EP 2004009002 W 20040812; ES 04764006 T 20040812; HR P20070520 T 20071112; KR 20067004277 A 20060228; MX PA06002137 A 20040812; MY PI20043367 A 20040818; NZ 54505104 A 20040812; PL 04764006 T 20040812; PT 04764006 T 20040812; RU 2006110045 A 20040812; TW 93125666 A 20040826; UA A200602214 A 20040812; US 14166308 A 20080618; US 56930606 A 20060221; ZA 200601687 A 20060227